

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Field Device Integration (FDI) –
Part 7: FDI Communication Devices**

**Intégration des appareils de terrain (FDI) –
Partie 7: Appareils de communication FDI**



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IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
Fax: +41 22 919 03 00
info@iec.ch
www.iec.ch

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE INTEGRATION (FDI) –

Part 7: FDI Communication Devices

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CDV	Report on voting
65E/350/CDV	65E/420/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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